- Single-Chip and Single-Supply Interface for IBM™ PC/AT™ Serial Port
- **RS-232 Bus-Pin ESD Protection Exceeds** ±15 kV Using Human-Body Model (HBM)
- Meets or Exceeds the Requirements of TIA/EIA-232-F and ITU v.28 Standards
- Operates With 3-V to 5.5-V V_{CC} Supply
- **Three Drivers and Five Receivers**
- Operates Up To 250 kbit/s
- Designed to Transmit at a Data Rate of 250 kbit/s
- Low Standby Current . . . 1 µA Typical
- External Capacitors . . . $4 \times 0.1 \mu F$
- Accepts 5-V Logic Input With 3.3-V Supply
- **Always-Active Noninverting Receiver** Output (ROUT2B)
- Designed to Be Interchangeable With Maxim MAX3243
- **Alternative High-Speed Pin-Compatible** Device (1 Mbit/s)
 - SNx5C3243
- Serial-Mouse Driveability
- **Auto-Powerdown Feature to Disable Driver** Outputs When No Valid RS-232 Signal Is Sensed
- **Applications**
 - Battery-Powered Systems, PDAs, Notebooks, Laptops, Palmtop PCs, and **Hand-Held Equipment**

(TOP VIEW) C2+ 28**∏** C1+ C2- Π_2 V**−∏**3 26 VCC RIN1 II4 25 **∏** GND RIN2∏5 24 ∏ C1-23 TORCEON RIN3∏6 22 FORCEOFF RIN4∏7 21 NVALID RIN5∏8 DOUT1 9 20 ROUT2B DOUT2 10 19 **∏** ROUT1 18 ROUT2 DOUT3 11

17 **∏** ROUT3

16 ROUT4

15 ROUT5

DIN3 112

DIN2 13

DIN1 **1**14

DB, DW, OR PW PACKAGE

description/ordering information

The MAX3243 consists of three line drivers, five line receivers, and a dual charge-pump circuit with ±15-kV ESD (HBM) protection pin to pin (serial-port connection pins, including GND). The device meets the requirements of TIA/EIA-232-F and provides the electrical interface between an asynchronous communication controller and the serial-port connector. This combination of drivers and receivers matches that needed for the typical serial port used in an IBM PC/AT, or compatible. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. In addition, the device includes an always-active noninverting output (ROUT2B), which allows applications using the ring indicator to transmit data while the device is powered down. The device operates at data signaling rates up to 250 kbit/s and a maximum of 30-V/µs driver output slew rate.



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description/ordering information (continued)

Flexible control options for power management are available when the serial port is inactive. The auto-powerdown feature functions when FORCEON is low and FORCEOFF is high. During this mode of operation, if the device does not sense a valid RS-232 signal, the driver outputs are disabled. If FORCEOFF is set low, both drivers and receivers (except ROUT2B) are shut off, and the supply current is reduced to 1 µA. Disconnecting the serial port or turning off the peripheral drivers causes the auto-powerdown condition to occur.

Auto-powerdown can be disabled when FORCEON and FORCEOFF are high and should be done when driving a serial mouse. With auto-powerdown enabled, the device is activated automatically when a valid signal is applied to any receiver input. The INVALID output is used to notify the user if an RS-232 signal is present at any receiver input. INVALID is high (valid data) if any receiver input voltage is greater than 2.7 V or less than -2.7 V or has been between -0.3 V and 0.3 V for less than 30 μs. INVALID is low (invalid data) if all receiver input voltages are between –0.3 V and 0.3 V for more than 30 μs. Refer to Figure 5 for receiver input levels.

ORDERING INFORMATION

TA	PACKAG	ΕŤ	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	COIC (DW)	Tube of 20	MAX3243CDW	MAY20420
	SOIC (DW)	Reel of 1000	MAX3243CDWR	MAX3243C
0°C to 70°C	000D (DD)	Tube of 50	MAX3243CDB	MAN/00400
	SSOP (DB)	Reel of 2000	MAX3243CDBR	MAX3243C
	TSSOP (PW)	Tube of 50	MAX3243CPW	14400400
		Reel of 2000	MAX3243CPWR	MA3243C
		Tube of 20	MAX3243IDW	MANAGAGI
	SOIC (DW)	Reel of 1000	MAX3243IDWR	MAX3243I
4000 1- 0500	000D (DD)	Tube of 50	MAX3243IDB	MAN VOO 401
–40°C to 85°C	SSOP (DB)	Reel of 2000	MAX3243IDBR	MAX3243I
	TCCOD (DW)	Tube of 50	MAX3243IPW	MP2040I
	TSSOP (PW)	Reel of 2000	MAX3243IPWR	MB3243I

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Function Tables

EACH DRIVER

		INPUTS		OUTPUT	
DIN	FORCEON	FORCEOFF	VALID RIN RS-232 LEVEL	DOUT	DRIVER STATUS
Х	Χ	L	Х	Z	Powered off
L	Н	Н	Х	Н	Normal operation with
Н	Н	Н	X	L	auto-powerdown disabled
L	L	Н	Yes	Н	Normal operation with
Н	L	Н	Yes	L	auto-powerdown enabled
L	L	Н	No	Z	Powered off by
Н	L	Н	No	Z	auto-powerdown feature

H = high level, L = low level, X = irrelevant, Z = high impedance

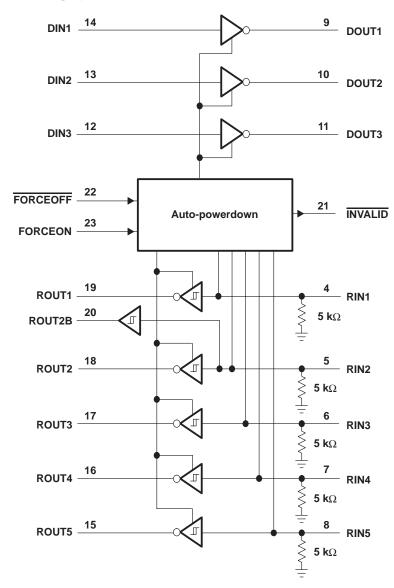


EACH RECEIVER

		INPUTS		OUTP	UTS	
RIN2	RIN1, RIN3–RIN5	FORCEOFF	VALID RIN RS-232 LEVEL	ROUT2B	ROUT	RECEIVER STATUS
L	Χ	L	Х	L	Z	Powered off while
Н	Χ	L	X	Н	Z	ROUT2B is active
L	L	Н	Yes	L	Н	
L	Н	Н	Yes	L	L	Normal operation with
Н	L	Н	Yes	Н	Н	auto-powerdown
Н	Н	Н	Yes	Н	L	disabled/enabled
Open	Open	Н	No	L	Н	

H = high level, L = low level, X = irrelevant, Z = high impedance (off), Open = input disconnected or connected driver off

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC} (see Note 1)	0.3 V to 6 V
Positive output supply voltage range, V+ (see Note 1)	
Negative output supply voltage range, V– (see Note 1)	
Supply voltage difference, V+ – V– (see Note 1)	13 V
Input voltage range, V _I : Driver (FORCEOFF, FORCEON)	0.3 V to 6 V
Receiver	–25 V to 25 V
Output voltage range, V _O : Driver	13.2 V to 13.2 V
Receiver (INVALID)	\dots -0.3 V to V _{CC} + 0.3 V
Package thermal impedance, θ _{JA} (see Notes 2 and 3): DB package	62°C/W
DW package	46°C/W
PW package	62°C/W
Operating virtual junction temperature, T _J	150°C
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltages are with respect to network GND.
 - 2. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4 and Figure 6)

				MIN	NOM	MAX	UNIT
	Supply voltage		V _{CC} = 3.3 V	3	3.3	3.6	
			V _{CC} = 5 V	4.5	5	5.5	V
.,	IH Driver and control high-level input voltage DIN, FORCE	DIN FORCES FORCES	V _{CC} = 3.3 V	2			
VIH	Driver and control nign-level input voltage	DIN, FORCEOFF, FORCEON	V _{CC} = 5 V	2.4			V
VIL	Driver and control low-level input voltage	DIN, FORCEOFF, FORCEON				8.0	V
٧ _I	Driver and control input voltage	DIN, FORCEOFF, FORCEON		0		5.5	V
٧ _I	Receiver input voltage			-25		25	V
т.			MAX3243C	0		70	°C
TA	Operating free-air temperature		MAX3243I	-40		85	C

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAME	TER	TES	T CONDITIONS	MIN	TYP‡	MAX	UNIT
II	Input leakage current	FORCEOFF, FORCEON				±0.01	±1	μΑ
		Auto-powerdown disabled		No load, FORCEOFF and FORCEON at V _{CC}		0.3	1	mA
Icc	Supply current	Powered off	$V_{CC} = 3.3 \text{ V or 5 V},$	No load, FORCEOFF at GND		1	10	
100	Сирру бинопс	Auto-powerdown enabled	T _A = 25°C	No load, FORCEOFF at V _{CC} , FORCEON at GND, All RIN are open or grounded, All DIN are grounded		1	10	μΑ

 $[\]ddagger$ All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.



DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Vон	High-level output voltage	All DOUT at R _L = 3 k Ω to GND	5	5.4		V
VOL	Low-level output voltage	All DOUT at R _L = 3 k Ω to GND		-5.4		V
Vo	Output voltage (mouse driveability)	DIN1 = DIN2 = GND, DIN3 = V_{CC} , 3-k Ω to GND at DOUT3, DOUT1 = DOUT2 = 2.5 mA	±5			٧
lН	High-level input current	VI = VCC		±0.01	±1	μΑ
I _{IL}	Low-level input current	V _I at GND		±0.01	±1	μΑ
	Ob and administration of a summer of the	$V_{CC} = 3.6 \text{ V}, \qquad \qquad V_{O} = 0 \text{ V}$.05	.00	4
los	Short-circuit output current‡	$V_{CC} = 5.5 \text{ V},$ $V_{O} = 0 \text{ V}$	±35		±60	mA
r _O	Output resistance	V_{CC} , V+, and V- = 0 V, V_{O} = ±2 V	300	10M		Ω
l _{off}	Output leakage current	$\overline{\text{FORCEOFF}} = \text{GND}, \qquad \text{V}_{\text{O}} = \pm 12 \text{ V}, \qquad \text{V}_{\text{CC}} = 0 \text{ to } 5.5 \text{ V}$			±25	μΑ

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V \pm 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER	TEST CONDITIONS		MIN	TYP†	MAX	UNIT
	Maximum data rate	C _L = 1000 pF, One DOUT switching,	$R_L = 3 k\Omega$, See Figure 1	150	250		kbit/s
t _{sk(p)}	Pulse skew§	C _L = 150 pF to 2500 pF	R_L = 3 kΩ to 7 kΩ, See Figure 2		100		ns
SR(tr)	Slew rate, transition region	V _{CC} = 3.3 V,	$C_L = 150 \text{ pF to } 1000 \text{ pF}$	6		30	\//uo
SK(II)	(see Figure 1)	V_{CC} = 3.3 V, R _L = 3 kΩ to 7 kΩ	C _L = 150 pF to 2500 pF	4		30	V/μs

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

NOTE 4: Test conditions are C1-C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2-C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.



^{\$} Short-circuit durations should be controlled to prevent exceeding the device absolute power dissipation ratings, and not more than one output should be shorted at a time.

[§] Pulse skew is defined as |tplh - tphl| of each channel of the same device.

RECEIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Vон	High-level output voltage	$I_{OH} = -1 \text{ mA}$	V _{CC} -0.6 V	V _{CC} -0.1 V		V
VOL	Low-level output voltage	I _{OL} = 1.6 mA			0.4	V
.,	Desilies and a least three held selfens	V _{CC} = 3.3 V		1.6	2.4	.,
V _{IT+}	Positive-going input threshold voltage	$V_{CC} = 5 V$		1.9	2.4	V
.,	Name Commission Council the make all development	V _{CC} = 3.3 V	0.6	1.1		.,
V _{IT} –	Negative-going input threshold voltage	V _{CC} = 5 V	0.8	1.4		V
V _{hys}	Input hysteresis (V _{IT+} - V _{IT-})			0.5		V
l _{off}	Output leakage current (except ROUT2B)	FORCEOFF = 0 V		±0.05	±10	μΑ
rį	Input resistance	$V_I = \pm 3 \text{ V to } \pm 25 \text{ V}$	3	5	7	kΩ

 $[\]overline{\dagger}$ All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V \pm 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4)

PARAMETER		TEST CONDITIONS	MIN TYPT	MAX	UNIT
tPLH	Propagation delay time, low- to high-level output	C 450 of Coo Figure 2	150		ns
tPHL	Propagation delay time, high- to low-level output	C _L = 150 pF, See Figure 3	150		ns
ten	Output enable time	0 450 5 5 0 0 0 0 5 5 5 5 5 5	200		ns
t _{dis}	Output disable time	$C_L = 150 \text{ pF}, R_L = 3 \text{ k}\Omega, \text{See Figure 4}$	200		ns
t _{sk(p)}	Pulse skew‡	See Figure 3	50		ns

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

‡ Pulse skew is defined as $|tp_{LH} - tp_{HL}|$ of each channel of the same device. NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.



AUTO-POWERDOWN SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

	PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
VT+(valid)	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND, FORCEOFF = V _{CC}			2.7	V
VT-(valid)	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND, FORCEOFF = V _{CC}	-2.7			V
VT(invalid)	Receiver input threshold for INVALID low-level output voltage	FORCEON = GND, FORCEOFF = V _{CC}	-0.3		0.3	V
VOH	INVALID high-level output voltage	I _{OH} = -1 mA, FORCEON = GND, FORCEOFF = V _{CC}	V _{CC} -0.6			V
VOL	INVALID low-level output voltage	I _{OL} = 1.6 mA, FORCEON = GND, FORCEOFF = V _{CC}			0.4	V

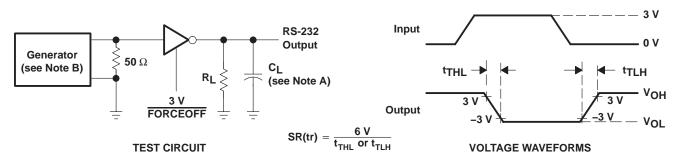
[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

	PARAMETER	MIN	TYP	MAX	UNIT
tvalid	Propagation delay time, low- to high-level output		1		μs
tinvalid	Propagation delay time, high- to low-level output		30		μs
t _{en}	Supply enable time		100		μs

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

PARAMETER MEASUREMENT INFORMATION

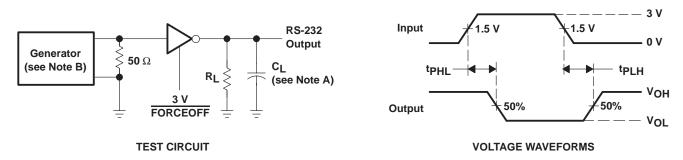


NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_r \le 10$ ns. $t_f \le 10$ ns.

Figure 1. Driver Slew Rate

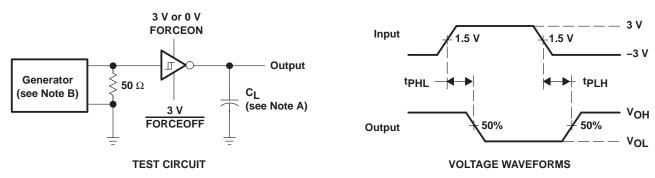
PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_r \le 10$ ns. $t_f \le 10$ ns.

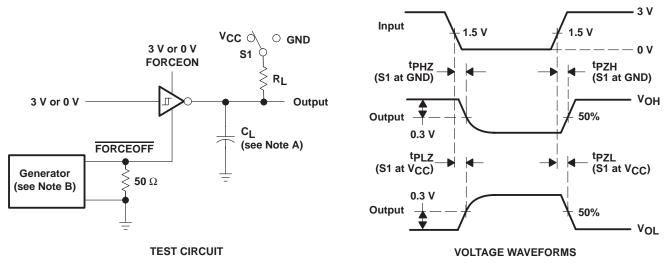
Figure 2. Driver Pulse Skew



NOTES: A. CL includes probe and jig capacitance.

B. The pulse generator has the following characteristics: $Z_O = 50 \Omega$, 50% duty cycle, $t_\Gamma \le 10$ ns, $t_f \le 10$ ns.

Figure 3. Receiver Propagation Delay Times



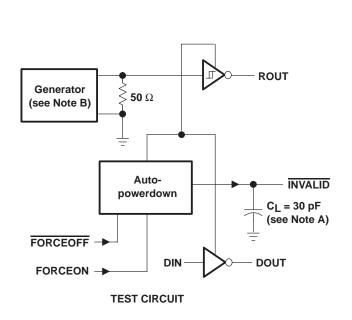
NOTES: A. C_L includes probe and jig capacitance.

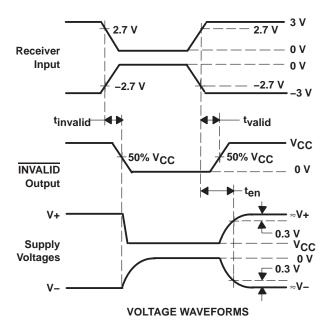
- B. The pulse generator has the following characteristics: $Z_O = 50 \Omega$, 50% duty cycle, $t_f \le 10$ ns. $t_f \le 10$ ns.
- C. tpLz and tpHz are the same as tdis.
- D. tpzL and tpzH are the same as ten.

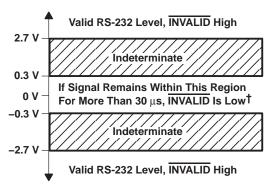
Figure 4. Receiver Enable and Disable Times



PARAMETER MEASUREMENT INFORMATION







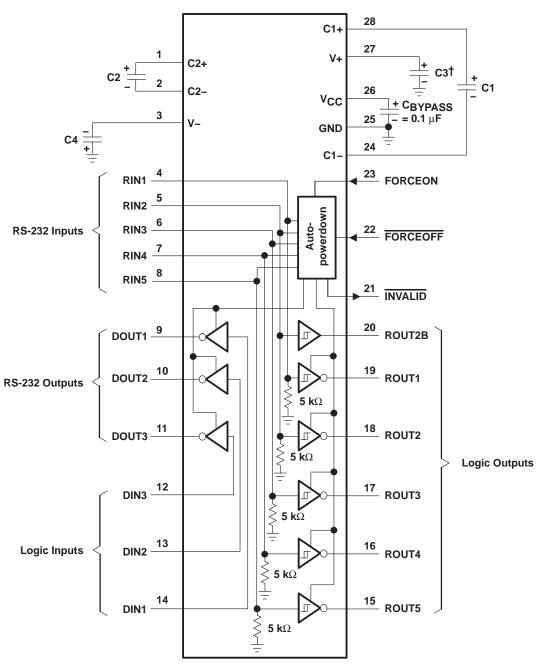
†Auto-powerdown disables drivers and reduces supply current to 1 µA.

NOTES: A. C_I includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 5 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_\Gamma \le 10$ ns. $t_f \le 10$ ns.

Figure 5. INVALID Propagation Delay Times and Supply Enabling Time

APPLICATION INFORMATION



†C3 can be connected to VCC or GND.

NOTES: A. Resistor values shown are nominal.

B. Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they should be connected as shown.

V_{CC} vs CAPACITOR VALUES

V _{CC}	C1	C2, C3, and C4
$\begin{array}{c} \textbf{3.3 V} \pm \textbf{0.3 V} \\ \textbf{5 V} \pm \textbf{0.5 V} \\ \textbf{3 V to 5.5 V} \end{array}$	0.1 μF 0.047 μF 0.1 μF	0.1 μF 0.33 μF 0.47 μF

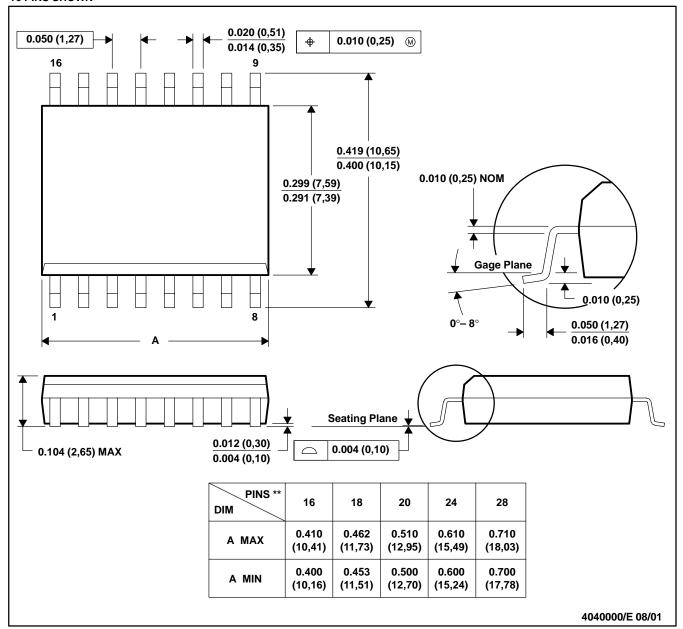
Figure 6. Typical Operating Circuit and Capacitor Values



DW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

16 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

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